

# **Product Compliance Declaration**

Please see <a href="https://www.molex.com">www.molex.com</a> for the most up-to-date information.

#### **Contact Information**

Name Molex Product Compliance E-Mail Product.Compliance@molex.com

#### **Part Information**

Part Number 0340833002 Part Weight 0.387G

Part Name MX150 RCPT 0.3 CABLE TIN 18/20AWG D WIND

## **Product Composition**

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
MX150 RCPT 0.3 CABLE TIN 18/20AWG D WIND	Component		100	0.387
HSM Copper	Material		100	0.387
HSM Copper Unplated	Material		98.8024	0.382365
Copper	Substance	7440-50-8	96.8758	0.374909
Nickel	Substance	7440-02-0	0.988	0.003824
Tin	Substance	7440-31-5	0.8892	0.003441
Phosphorus	Substance	7723-14-0	0.0494	0.000191
Nickel Plating	Material		0.329	0.001273
Nickel	Substance	7440-02-0	0.329	0.001273
Further Additives, not to declare	Substance	system	3E-05	1E-07
Tin Plating	Material		0.5396	0.002088
Tin	Substance	7440-31-5	0.5396	0.002088
Copper Plating	Material		0.329	0.001273

#### Form Rev - F

Limitation of this Product Compliance Declaration: This declaration is based on the state of knowledge and belief of Molex as of the date that it is provided. Molex bases its knowledge and belief on information provided by numerous sources, including third parties, and in certain circumstances laboratory test results. Molex has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and substances. Molex represents that to the best of its knowledge that the information provided in this declaration is accurate. Molex's sole liability shall be to either replace the product or refund the purchase price of the product if it does not meet the requirement of this declaration.

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Copper	Substance	7440-50-8	0.329	0.001273

#### **HFLH** Declaration Information

Regulatory Revision IEC 61249-2-21

**Contained Substances Exceeding Threshold** 

Not reviewed

#### **ROHS Declaration Information**

Regulatory Revision EU 2015/863

Compliance Status Compliant

**Contained Substances Exceeding Threshold** 

None

**Exemptions** 

None

#### **REACH-SVHC Declaration Information**

**Regulatory Revision** D(2020)9139-DC (19 Jan 2021)

**Contained Substances Exceeding Threshold** 

None

# **GADSL Declaration Information**

Regulatory Revision GADSL imported from IMDS

## **Contained Substances Exceeding Threshold**

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
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Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
lead	e-plate Sn (electrodeposited Tin Coatings, bright and matt)	*Note	500	Yes
nickel powder [particle diameter < 1 mm]	High Copper Alloy (NB109)	*Note	10,000	Yes
nickel powder [particle diameter < 1 mm]	Ep-Ni	*Note	997,500	Yes
silver	High Copper Alloy (NB109)	*Note	500	Yes
copper	High Copper Alloy (NB109)	*Note	977,000	Yes
copper	e-plate Cu (electrodeposited Copper Coatings)	*Note	999,625	Yes

<sup>\*</sup>Note: For GADSL substance declarable/prohibited threshold values, please reference http://www.gadsl.org/

## **Exemptions**

Part Name	Exemption
e-plate Sn (electrodeposited Tin Coatings, bright and matt)	44 Concentration within acceptable GADSL limits
High Copper Alloy (NB109)	34 Not applicable
Ep-Ni	33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/cm2/week)

## **Process Information**

Component Plating / Surface Finish	N/A
Termination Base Alloy	N/A
Solder Alloy	N/A
Process Capability	N/A
Maximum Exposure Time (seconds)	N/A
Maximum Process Temperature (C)	N/A
Maximum Cycles at Reflow Temperature	N/A
J-STD-020 Moisture Sensitivity Level	N/A

Mar 18, 2021